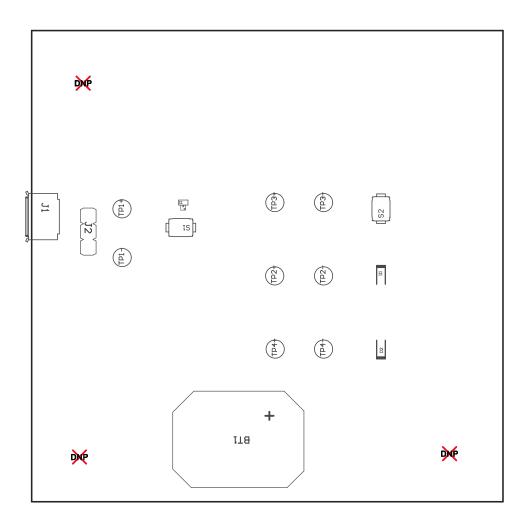
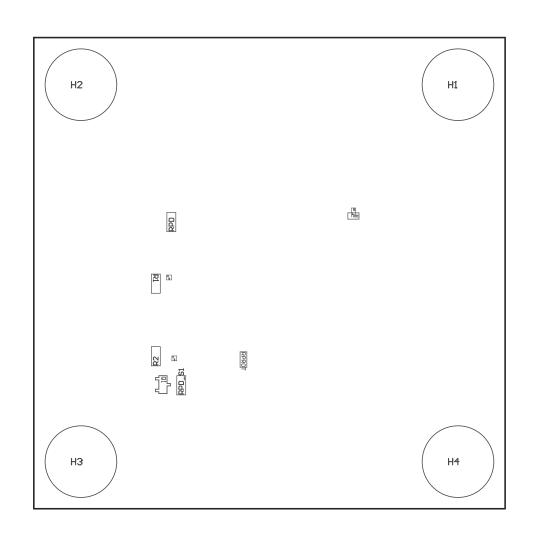
- mZZ2 These assemblies are ESD sensitive, ESD precautions shall be observed.
- ■ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ■ZZ4 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00556	REV: E2	SUN REU	: Not In VersionControl		
	TID #: 00556					
PLOT NAME = Top Assembly Drawing	GENERATED : 11/10/	2015 1:33:02	PM	TEXAS INSTRUMENTS		



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00556	REV: E2	SUN REV:	Not In VersionControl		
	TID #: 00556					
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/10/	2015 1:33:03	PM	TEXAS INSTRUMENTS		

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